IPC Web Site for Informat http://www.ipc.org/IPC-1 Supplier Information Company name* Onsemi Contact Name Product-Env-Stewards Authorized Representative*	Company u Title - Cont	nique ID	Form Type * Distribute	Cla		Homogeneous Mater					
Company name* onsemi Contact Name Product-Env-Stewards	Title - Cont	<u>.</u>		Unique ID Auth	ority		D)-4-*			
onsemi Contact Name Product-Env-Stewards	Title - Cont	<u>.</u>		Unique ID Auth	ority		В)_4_*			
Contact Name Product-Env-Stewards		act			Unique ID Authority			Response Date*			
Product-Env-Stewards		act						2023-06-08			
	Donato / P	uct		Phone - Contact*			Email - Contact*				
authorized Representative*	Product Env	viro Compliance		NA			Product-Env-Stewards@onsemi.com				
•	uthorized Representative* Title - Representative			Phone - Representative*			Email - Representative*				
Product-Env-Stewards	Product Env	oduct Enviro Compliance		NA	NA			Product-Env-Stewards@onsemi.com			
Requester Item Number N	Mfr Item Number	Mfr Item Name		Effective Date	Version	Manufacturing Site	We	ight*	UOM	Unit Type	
C	GBPC12005	BR GBPC GPPN 1	12A 50V	2023-06-08		TSCBE	16949.998		mg	Each	
Manufacturing Process Information							1			1	
Terminal Plating / Grid Array Material	Terminal Base	Alloy J-	STD-020 MSL Rating	Peak Proc	ess Body Temperatu	re Max Time at Peal	Max Time at Peak Temperature		e Number of Reflow Cycles		
Precious metal (e.g. Ag,Au, NiPdAu) Sn)	(no CU Alloy	loy NA		0	С	30	seconds	3			
Comments											
For more information regarding material comp											

RoHS Material Composition Declaration			Declaration Type *	Detailed					
RoHS Definition: Quantity limit of 0.01% by mass (100 PPM) in homogeneous material for Cadmium and quantity limit of 0.1% by mass (1000 PPM) in homogeneous material for: Lead (Pb), Mercury (Hg), Hexavalent Chromium (Cr6+), Polybrominated Biphenyls (PBB), Polybrominated Diphenyl Ethers (PBDE), and Bis(2-ethylhexyl) phthalate (DEHP), Benzyl-butyl phthalate (BBP), Dibutyl phthalate (DBP), Diisobutyl phthalate (DIBP).									
Please indicate whether any homogeneous material (as defined by the RoHS Directive, EU 2011/65/EU and implemented by the laws of the European Union member states) of the part identified on this form contains lead, mercury, cadmium, hexavalentchromium, polybrominated biphenyls and/or polybrominated diphenyl ethers (each a "RoHS restricted substance") in excess of the applicable quantity limit identified above. If a homogeneous material within the part contains a RoHS restricted substance inexcess of an applicable quantity limit, please indicate below which, if any, RoHS exemption you believe may apply. If the part is an assembly with lower level components, the declaration shall encompass all such components. Supplier certifies that it gathered the information it provides in this form using appropriate methods to ensure its accuracy and that such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products with European Union member state laws that implement the RoHS Directive. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its provided certifications regarding their contributions to the part, and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part, the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusivesource of the Supplier's Itaability and the Company's remedies for issues that arise regarding information the Supplier provides in this f									
RoHS Declaration * 4 - Item(s	s) does not contain RoHS restricted substance	ces per the definition above except for selected exer	nptions Supplier Acceptance	* Accepted					
Exemption: 7a: Lead in high melting temperature type solders (i.e. lead based solder alloys containing 85% by weight or more lead). Exemption: 7c-I Electrical and electronic components containing lead in a glass or ceramic other than dielectric ceramic in capacitors, e.g. piezoelectronic devices, or in a glass or ceramic matrix compound.									
Exemption List Version	EL-2011/534/EU								
Declaration Signature									
Instructions: Complete all of the required fields on all pages of this form. Select the "Accepted" on the Supplier Acceptance drop-down. This will display the signature area. Digitally sign the declaration (if required by the Requester) and click on Submit Form to have the form returned to the Requester.									
Supplier Digital Signature R		,							

Homogeneous Material Composition Declaration for Electronic Products

SubItem Instructions: The presence of any JIG Level A or B substances must be declared. [1] indicate the subpart in which the substance is located, [2] provide a description of the homogeneous material [3], enter the weight of the homogeneous material.

Substance Instructions: [A] select the Level (JIG A, JIG B, Requester or Supplier) [B] select the substance category (JIG or Requester) or enter a value (Supplier). [C] select the substance (JIG) or enter the substance and CAS (Other). [D] select a RoHS exemption, if applicable [E] enter the weight of the substance or the PPM concentration [F] Optionally enter the positive (+) and negative (-) tolerance in percent (Note: percent tolerance values are expected to cover a 3 sigma range of distribution unless otherwise noted).

Homogeneous Material	Weight	Unit of Measure	Level	Substance	CAS	Exempt	Weight	Unit of Measure
Case	2949.3	mg	Supplier	Ortho Cresol Novolac Resin	29690-82-2		589.8748	mg
			Supplier	Silica (SiO2)	14464-46-1		2064.5603	mg
			Supplier	Phosphorus (P)	7723-14-0		58.9152	mg
			Supplier	Phenolic Resin (Novolac)	9003-35-4		235.9497	mg
Die	33.561	mg	Supplier	Silicon (Si)	7440-21-3		30.2049	mg
			В	Nickel (Ni)	7440-02-0		0.2181	mg
			Supplier	Gold (Au)	7440-57-5		0.0503	mg
			Supplier	Lead Bisilicate	65997-18-4	7c	3.0876	mg
Die Attach Solder	18.1365	mg	Supplier	Silver (Ag)	7440-22-4		0.4534	mg
			A	Lead (Pb)	7439-92-1	7a	16.7763	mg
			Supplier	Tin (Sn)	7440-31-5		0.9068	mg
Die Attach Solder - Solder Wafer	82.8855	mg	Supplier	Silver (Ag)	7440-22-4		2.0721	mg
			A	Lead (Pb)	7439-92-1		76.6691	mg
			Supplier	Tin (Sn)	7440-31-5		4.1443	mg
Heat Sink	3803.24	mg	Supplier	Aluminum (Al)	7429-90-5		3803.24	mg
Lead Frame	1220.4	mg	Supplier	Iron (Fe)	7439-89-6		0.9763	mg
			Supplier	Copper (Cu)	7440-50-8		1219.1797	mg
			Supplier	Phosphorus (P)	7723-14-0		0.244	mg
Marking Ink	0.5085	mg	Supplier	Silicon Dioxide (SiO2)	112945-52-5		0.0254	mg
			Supplier	1-Hydroxycyclohexyl phenyl ketone	947-19-3		0.0254	mg
			Supplier	Padimate (C14H21NO2)	21245-01-2		0.0509	mg
			Supplier	2-Propenoic acid polymer	53192-18-0		0.3305	mg
			Supplier	Aluminum (Al)	7429-90-5		0.0763	mg
Mold Compound-White	6552.36	mg		Polymer Resin	proprietary data		1092.2784	mg
			Supplier	1,2-Bis(pentabromophenyl) ethane	84852-53-9		382.0026	mg
			Supplier	Brominated epoxy resin	Proprietary Data		1419.8964	mg
			В	Antimony Trioxide (Sb2O3)	1309-64-4		218.1936	mg
			Supplier	Carbon Black (C)	1333-86-4		54.3846	mg
			Supplier	Aluminum Hydroxide (Al(OH)3)	21645-51-2		655.236	mg
			Supplier	Fused Silica (SiO2)	60676-86-0		2730.3682	mg
Plating-2	14.916	mg	В	Nickel (Ni)	7440-02-0		14.916	mg
Terminal	2274.69	mg	Supplier	Iron (Fe)	7439-89-6		2.7296	mg

	Supplier	Copper (Cu)	7440-50-8	2270.9822	mg
	Supplier	Phosphorus (P)	7723-14-0	0.9781	mg